NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE20H11K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

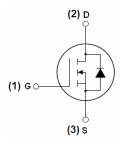
- V_{DS} =20V, I_D =110A $R_{DS(ON)}$ <4m Ω @ V_{GS} =10V (Typ3m Ω)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Load switching
- Uninterruptible power supply

100% UIS TESTED!

100% ΔVds TESTED!



Schematic diagram



Marking and pin assignment



TO-252-2L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE20H11K	NCE20H11K	TO-252-2L	-	-	-

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±12	V
Drain Current-Continuous	I _D	110	А
Drain Current-Continuous(T _C =100°C)	I _D (100℃)	77	А
Pulsed Drain Current	I _{DM}	200	Α
Maximum Power Dissipation	P _D	85	W
Single pulse avalanche energy (Note 5)	E _{AS}	450	mJ
Operating Junction and Storage Temperature Range	T_J , T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	R _{0JC}	1.5	°C/W



Electrical Characteristics (T_A=25°C unless otherwise noted)

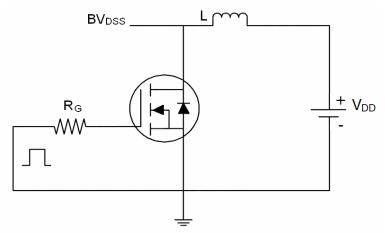
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	0.5	0.7	1.2	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =30A	-	3	4	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =30A	100	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ 40\/\/ 0\/		3000		PF
Output Capacitance	C _{oss}	V_{DS} =10V, V_{GS} =0V, F=1.0MHz		700		PF
Reverse Transfer Capacitance	C _{rss}	F=1.0IVID2		390		PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	12.5	-	nS
Turn-on Rise Time	t _r	VGS=10V,VDS=10V	-	35.5	-	nS
Turn-Off Delay Time	t _{d(off)}	RL=0. 5Ω ,RGEN= 3Ω	-	40	-	nS
Turn-Off Fall Time	t _f		-	32.5	-	nS
Total Gate Charge	Qg			30.4		nC
Gate-Source Charge	Q_{gs}	VGS=4.5V,VDS=10V,ID=30A		9.5		nC
Gate-Drain Charge	Q_{gd}			19.8		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-	-	1.2	V
Diode Forward Current (Note 2)	Is	-	-	-	110	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 30A	-	35.3	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	30.7	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

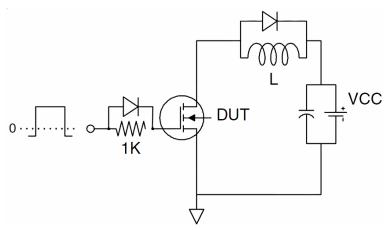
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- **4.** Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^{\circ}$ C,VDD=10V,VG=10V,L=0.5mH,Rg=25 Ω

Test circuit

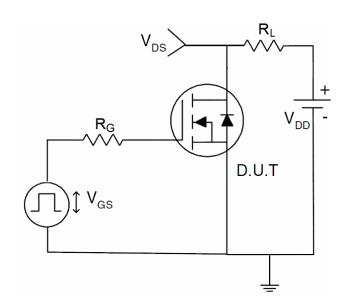
1) E_{AS} test Circuits



2) Gate charge test Circuit:



3) Switch Time Test Circuit:



Typical Electrical and Thermal Characteristics (Curves)

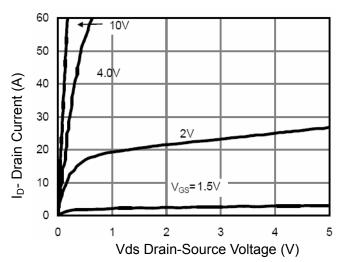


Figure 1 Output Characteristics

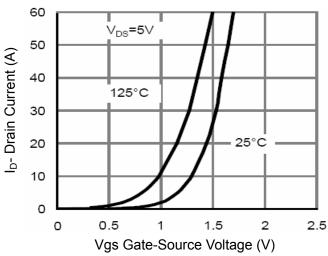


Figure 2 Transfer Characteristics

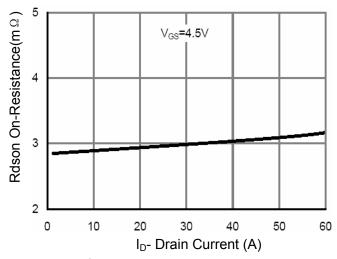


Figure 3 Rdson- Drain Current

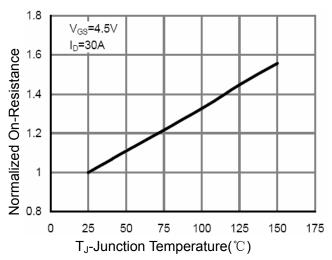


Figure 4 Rdson-Junction Temperature

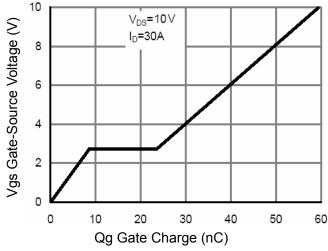


Figure 5 Gate Charge

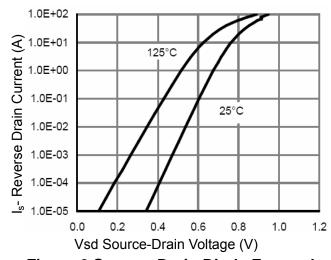


Figure 6 Source- Drain Diode Forward



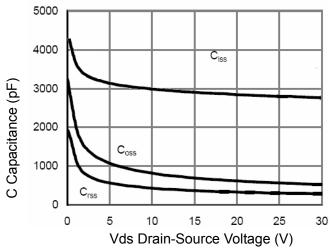


Figure 7 Capacitance vs Vds

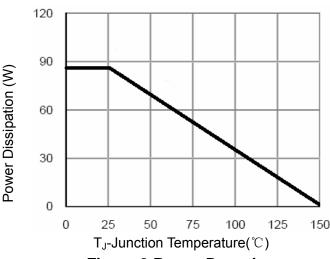


Figure 9 Power De-rating

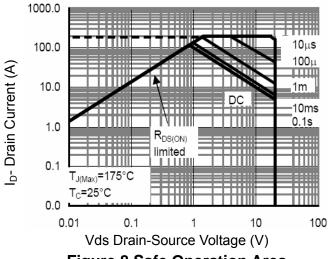


Figure 8 Safe Operation Area

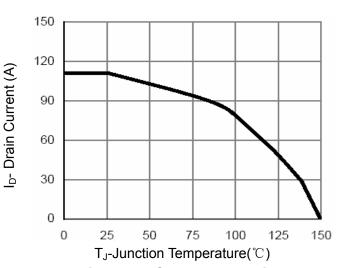


Figure 10 Current De-rating

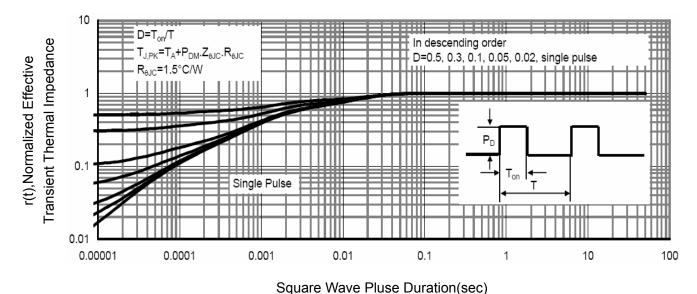
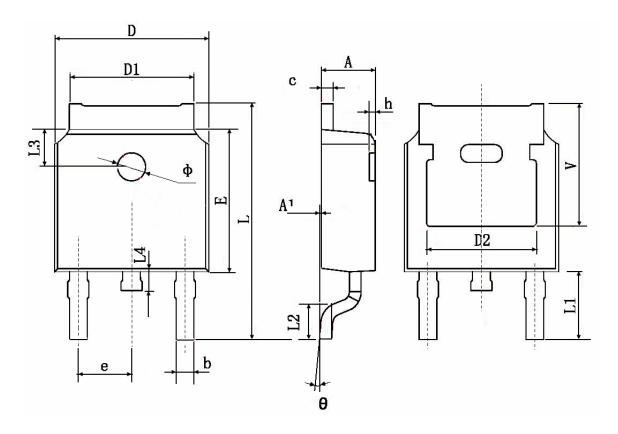


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252 Package Information



Symbol	Dimensions I	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483	0.483 TYP.		TYP.	
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900	2.900 TYP.		TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.600	1.600 TYP.		TYP.	
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		

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